

# HRPPD Meeting #22 Update

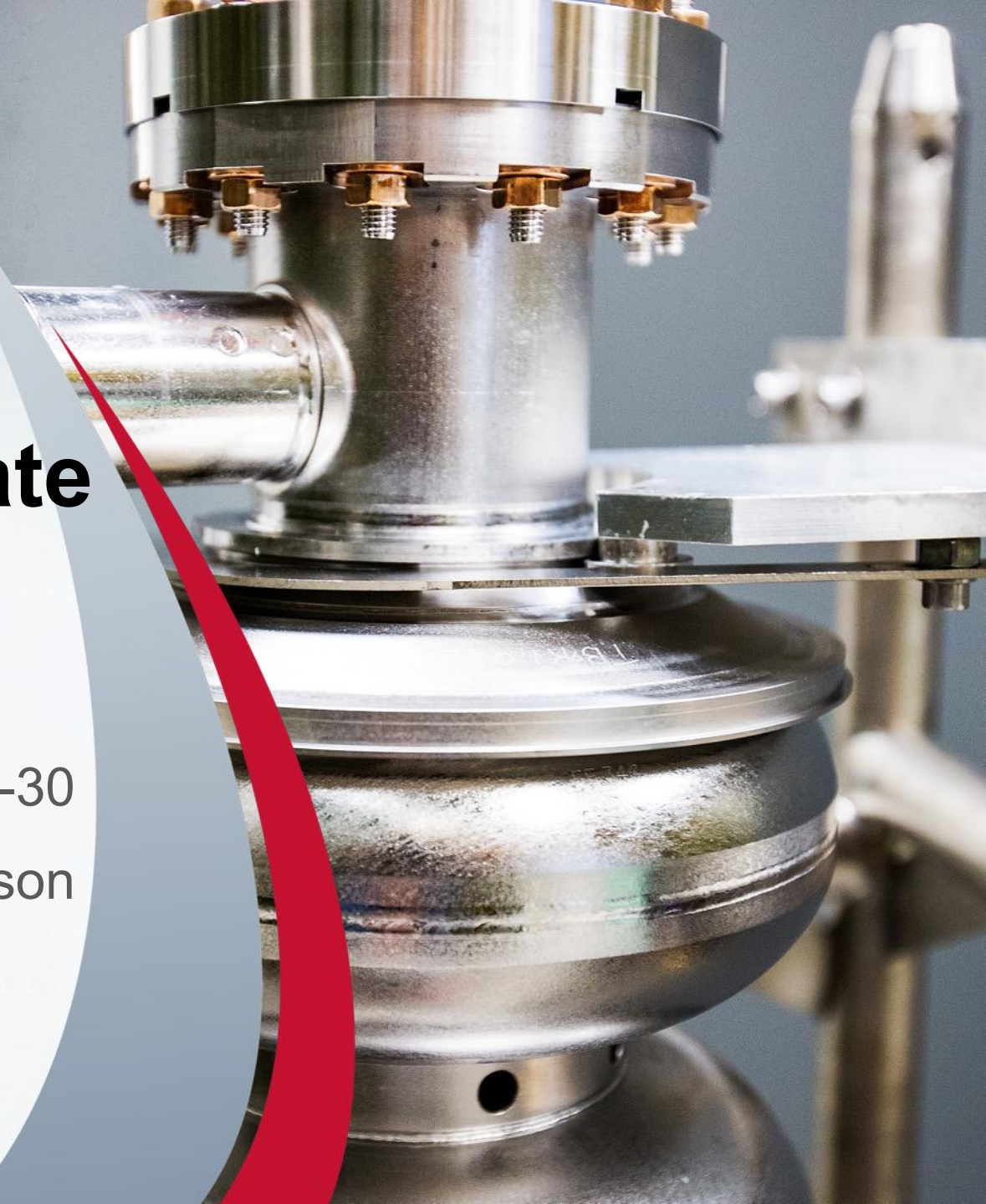
2026-06-30

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U.S. DEPARTMENT  
of ENERGY



# Current Status

## Tasks:

- **Priority tasks**

- HRPPD order status
  - Submitted 6/17, due 10/21
- FCFD
  - Is Ray testing at BNL in July for hpDIRC needs?
- Interposer order to be submitted by July 1
  - RFQ in progress
  - Final thickness reduced to 3mm
  - Order qty 208 covers 13 HRPPDs
- Review preliminary mechanical envelope and cooling

- **Upcoming items**

- FCFD specs for pfRICH and hpDIRC to be finalized end of July?
  - Will review at Glasgow Collab
- Analyze signal path length and test on-board terminations to FCFD
- FCFDv1.2 FEBs
- Aiming for backplane order submitted by mid-August
  - Need to select HV connectors and reroute signals to reduce length
  - Start finalizing LV/HV power distribution, bridge card + VTRX+ for ASIC cards
- Spacer/shims/sidewall/window need to be ordered by HRPPD arrival

## No update

- Open items:
  - N/A
- FCFD Test Board
  - Will resume in July
- Backplane Changes
  - See action item list

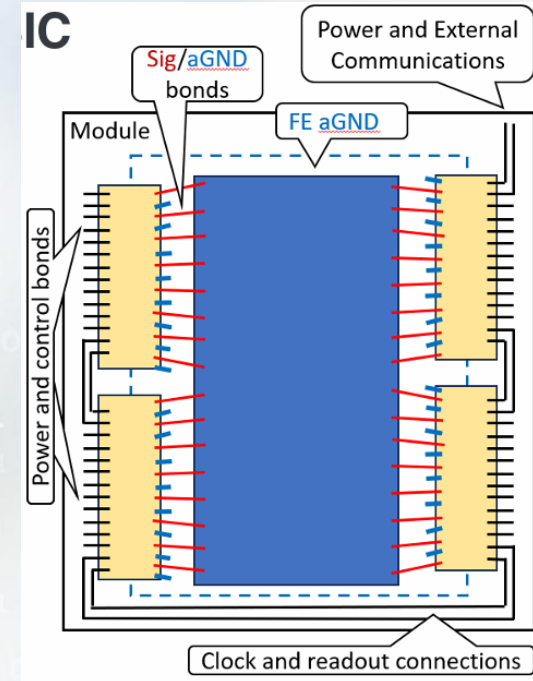
# Mechanical Envelope

## Notes

- [Link to model](#)
- Maximum height is 50 mm
  - Measured from window or lip?
- ASIC cards
  - FCFD estimated size 15x3 mm for 32 channels
    - Will need to be mindful of thickness of final board and connector, will require 10-12 layers
  - Used card edge connector on top side for expediency, probably a better solution
  - Connector height is estimated from FNAL estimate
  - ASICs may be wirebonded so no room for cooling pipes on ASIC side
    - Wirebonds will need protection
- Bridge card
  - bPOL model based off OTS CERN module, not sure if we will use custom
  - 2x VTRX+ modules included in model
    - Brian suggested more modules for redundancy and limit data loss on part failure
- How to reduce height?
  - Ballpark target height = 45 mm  $\pm$  10%?
  - ASIC card height could be reduced by ~2 mm
  - Shorten top side ASIC card connector

- Chip 3mm
  - Sensor-ASIC gap 2-3mm
  - Back-side bonds 1mm
  - Extra routing area 2mm
  - pcb edge clearance 0.5mm
- 
- **Total 8.5-9.5mm**

## FNAL Estimate

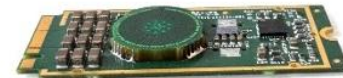
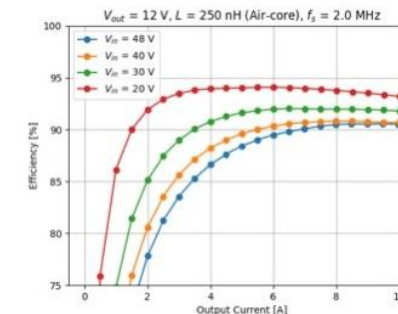


## bPOL48V module

Module optimised in volume, available in large numbers

Hosting:

- CERN GaN\_controller ASIC
- CERN custom PCB air core inductor
- Commercial Gallium Nitride power stage



55mm x 24mm x 3mm

# Appendix